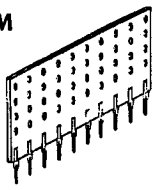
CAPITAL ADVANCED TECHNOLOGIES INC. ™

SINGLE-IN-LINE UNIVERSAL BOARDS

UNI-SIP ™

UNIVERSAL SINGLE-IN-LINE PACKAGE

GET YOUR PARTS
" IN-LINE " ™

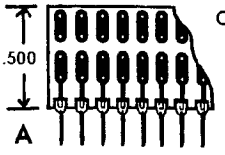


MINIATURE BREADBOARD MODULES FEATURE PINS ON .100 CENTERS

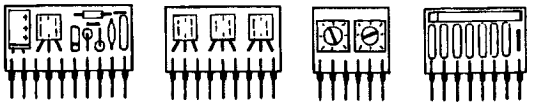
OFFER USEFUL HOLE PATTERNS AND PAD DESIGNS

COMPATIBLE WITH STANDARD BREADBOARDS, SOCKETS, AND SOLDERLESS BREADBOARDS USING .1 CENTERLINES

1000 SERIES FOR BASIC NETWORKS AND COMPONENT ARRAYS

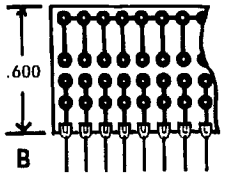


Comparable in cost to standard headers per pin, yet much more versatile.

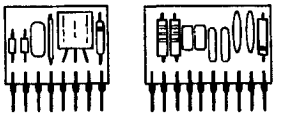


AVAILABLE IN 6, 7, 8, 9, and 10 PIN MODELS. Excellent for prototype or production circuits.

2000 SERIES ACCEPTS COMPONENTS ON .1, .2, .3, or .4 CENTERS



The 2000 series provides a common buss for network applications. Define the buss common pin by installing a jumper where desired.

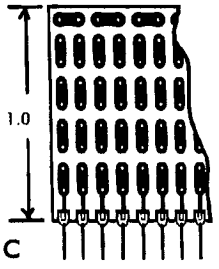


Simply cut foils to tailor board to your needs.



AVAILABLE IN 6, 7, 8, 10, and 12 PIN MODELS. Foil modifications expand layout options.

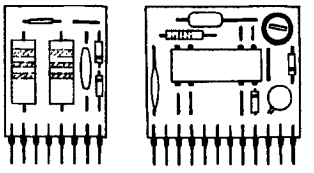
3000 SERIES FOR HIGHER DENSITY GENERAL PURPOSE APPLICATIONS



SIMILAR TO 1000 SERIES BUT LARGER (1.0 in.)

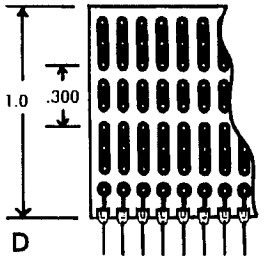
2 HOLES PER PAD

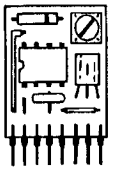
PATTERN ACCEPTS WIDE RANGE OF DEVICES



AVAILABLE IN 8, 10, 12, and 14 PIN MODELS. For general use applications where compatibility with a large number of device sizes is desirable. Features 2 holes per pad on a .100 matrix.

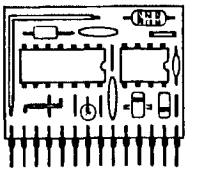
4000 SERIES ACCEPTS DIPS ON STANDARD .300 CENTERLINE





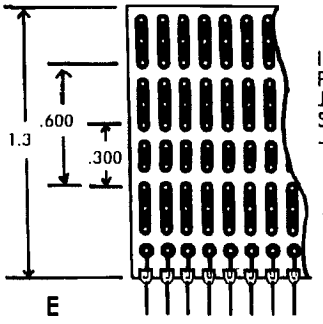
EXCELLENT FOR WORK WITH I.C.s

INPUT/OUTPUT PINS JUMPER SELECTABLE.



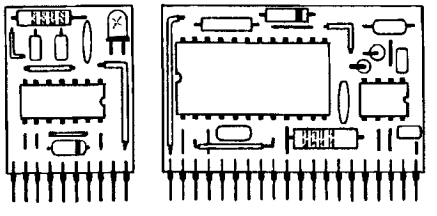
AVAILABLE IN 7, 8, 10, 12, 14, and 16 PIN MODELS. Make selection based on signal connections required. Example: 8 pin model can support 1-16 pin Dip, with 8 signal lines (pins).

5000 SERIES ACCEPTS STANDARD .300 or .600 CENTERLINE DIPS



OUR MOST VERSATILE SERIES FOR USE WITH I.C.s

IN/OUT PINS JUMPER SELECT--ABLE



AVAILABLE IN 8, 10, 12, 14, 16, and 20 PIN MODELS. Centerlines for .300 and .600 Dips. 20 pin model can hold 1-40 pin Dip with 20 signal lines to input/output pins.

From simple networks and component arrays to I.C. circuits using up to .600 wide Dips, UNI-SIP breadboards offer the perfect packaging solution for building both prototype and production thru-hole circuit modules.

Use a solderless breadboard to test your idea, use a UNI-SIP breadboard to " KEEP IT ". ™

SPECIFICATIONS

BOARD MATERIAL: G-10 FR-4 GLASS EPOXY
THICKNESS: .032 +-.005
FOILS: SOLDER COATED 1oz. COPPER 1-SIDE
HOLES: .036 DIAMETER +-.003
PINS: .1 CENTERS +-.004. PIN LENGTH: .130 +-.010
Pins are soldered in position
BOARD TOLERANCES: +-.015 TYP. OVERALL
ALL DIMENSIONS SHOWN ARE IN INCHES

AVAILABILITY / PRICING
PLEASE CALL FOR VOLUME PRICING

Fig.	No. Pins	Board Width	Part Number	
			1000 SERIES	
A	6	.6	US-1006	
A	7	.7	US-1007	
A	8	.8	US-1008	
A	9	.9	US-1009	
A	10	1.0	US-1010	
			2000 SERIES	
B	6	.6	US-2006	
B	7	.7	US-2007	
B	8	.8	US-2008	
B	10	1.0	US-2010	
B	12	1.2	US-2012	
			3000 SERIES	
C	8	.8	US-3008	
C	10	1.0	US-3010	
C	12	1.2	US-3012	
C	14	1.4	US-3014	
			4000 SERIES	
D	7	.7	US-4007	
D	8	.8	US-4008	
D	10	1.0	US-4010	
D	12	1.2	US-4012	
D	14	1.4	US-4014	
D	16	1.6	US-4016	
			5000 SERIES	
E	8	.8	US-5008	
E	10	1.0	US-5010	
E	12	1.2	US-5012	
E	14	1.4	US-5014	
E	16	1.6	US-5016	
E	20	2.0	US-5020	

* Denotes single piece packaged product price. Call for volume discount price on large quantities.